PRESS RELEASE

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MicroWave Technology Inc. Releases GaAs Based Advanced MMIC Products Compatible with both Epoxy and AuSn Eutectic Die Attachment Processes

Fremont, CA. November 18, 2014 – MicroWave Technology Inc. (MwT), a division of IXYS Corporation (NASDAQ: IXYS), announced that it offers a family of MMIC products that are fully compatible with both epoxy and AuSn eutectic alloy die attachment methods.

Many of the GaAs based MMIC products on the market can only use epoxy for die attachment process while certain commercial, military, and high reliability/space applications will demand eutectic die attachment process instead of epoxy process. The eutectic die attach process provides improved electrical performance and thermal dissipation, which enhances long term reliability of the MMIC parts under operation. MwT has recently converted its key MMIC products to have the compatibility of both eutectic and epoxy die attachment processes. In this unique device technology, a special non-wet metal layer is placed to the backside via holes regions to prevent the melted AuSn eutectic alloy from penetrating through the backside via holes, causing the damages for the features/circuitries on the front side of the MMIC chip during the die attachment process.

“This unique technology feature will allow our customers to utilize our high performance GaAs based MMIC products for applications that demand robustness and stringent long term reliability,” stated Dr. Greg Zhou, General Manager of MicroWave Technology Inc. “We have already had several key MMIC products with the eutectic die attachment compatibility designed into various sockets and have begun receiving the production orders for these MMIC products.”

For detailed information and datasheets of MwT GaAs based MMIC and discrete devices, please visit the MwT website at www.mwtinc.com, or contact MwT Sales at info@mwtinc.com or call (510) 651-6700 for sample requests and price quotes for the MMIC products with backside metal scheme compatible with both epoxy and AuSn Eutectic die attachment processes.

About MicroWave Technology Inc.

MwT is a leading manufacturer of radio frequency (RF) and microwave frequency discrete semiconductor products, advanced MMIC’s, hybrid modules, and amplifiers for
wireless communication infrastructure, military/aerospace, industrial, and medical applications. MwT houses one of four IXYS fab facilities, offering a factory specializing in GaAs based semiconductor and hybrid microwave integrated circuitry (HMIC) manufacturing.

About IXYS Corporation

IXYS Corporation makes and markets technology-driven products to improve power conversion efficiency, generate solar and wind power, and provide efficient motor control for industrial applications. IXYS offers a diversified product base that addresses worldwide needs for power control, electrical efficiency, renewable energy, telecommunications, medical devices, electronic displays and RF power.

Safe Harbor Statement

Any statements contained in this press release that are not statements of historical fact, including the performance, features and suitability of products for various applications, may be deemed to be forward-looking statements. There are a number of important factors that could cause the results of IXYS to differ materially from those indicated by these forward-looking statements, including, among others, risks detailed from time to time in the Company's SEC reports, including its Form 10-Q for the quarter ended September 30, 2014. The Company undertakes no obligation to publicly release the results of any revisions to these forward-looking statements.